

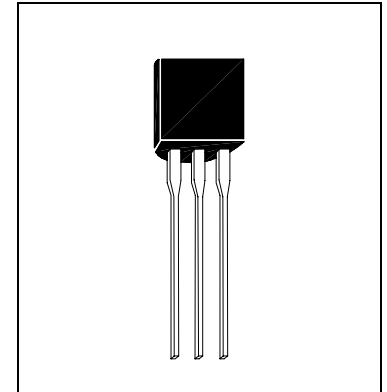


H2N5087

PNP EPITAXIAL PLANAR TRANSISTOR

Description

This device was designed for low noise, high gain, general purpose amplifier applications for 1uA to 25mA collector current.



Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 625 mW
- Maximum Voltages and Currents (Ta=25°C)
 VCBO Collector to Base Voltage -50 V
 VCEO Collector to Emitter Voltage -50 V
 VEBO Emitter to Base Voltage -3 V
 IC Collector Current -50mA

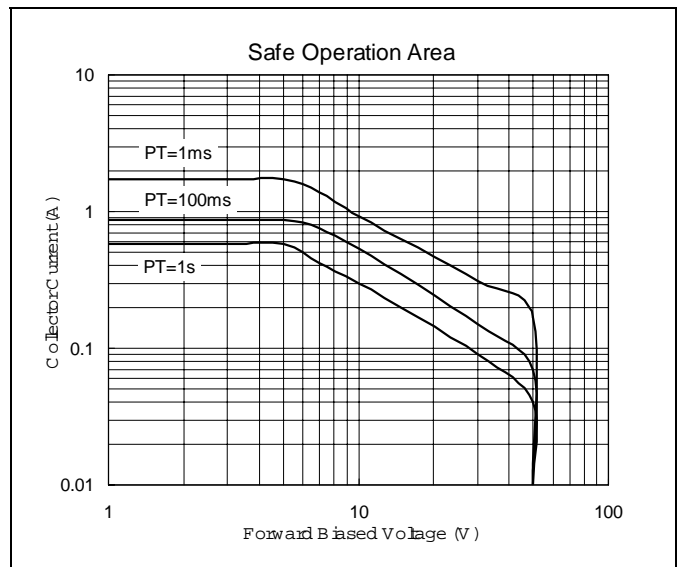
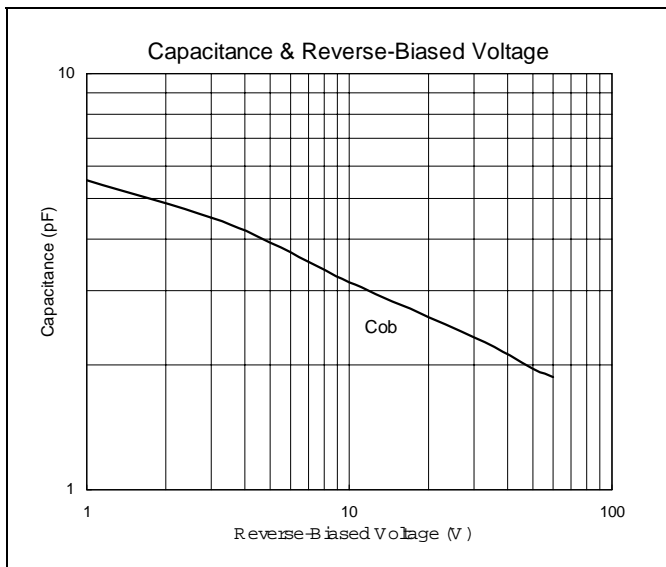
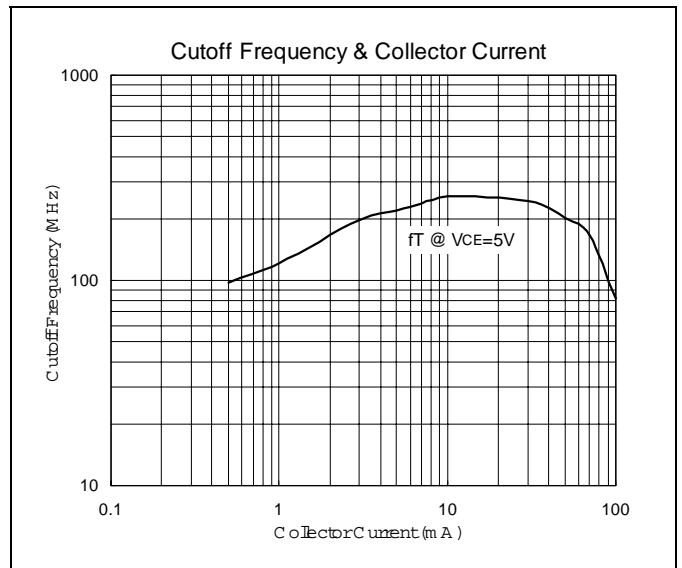
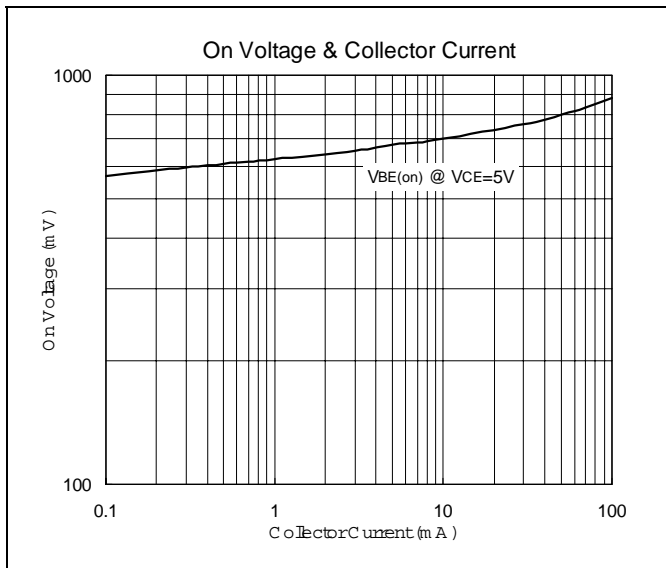
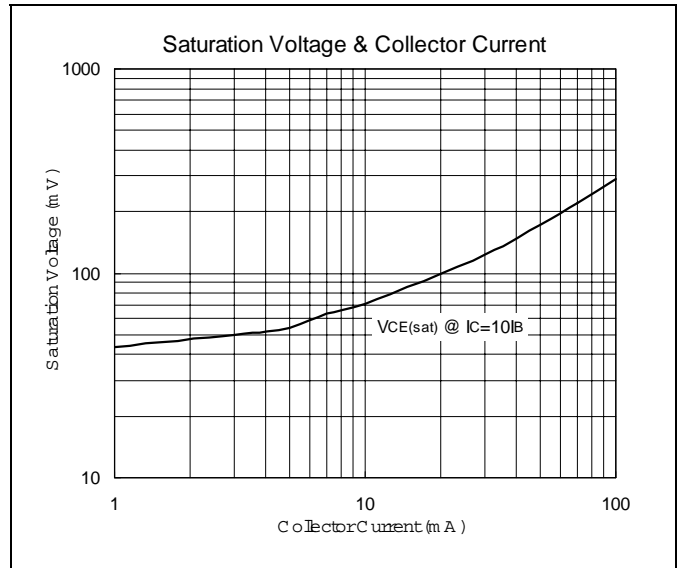
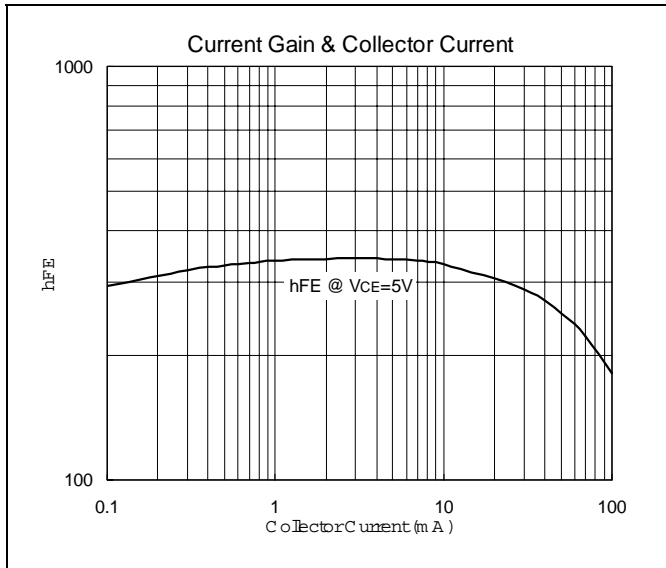
Characteristics (Ta=25°C)

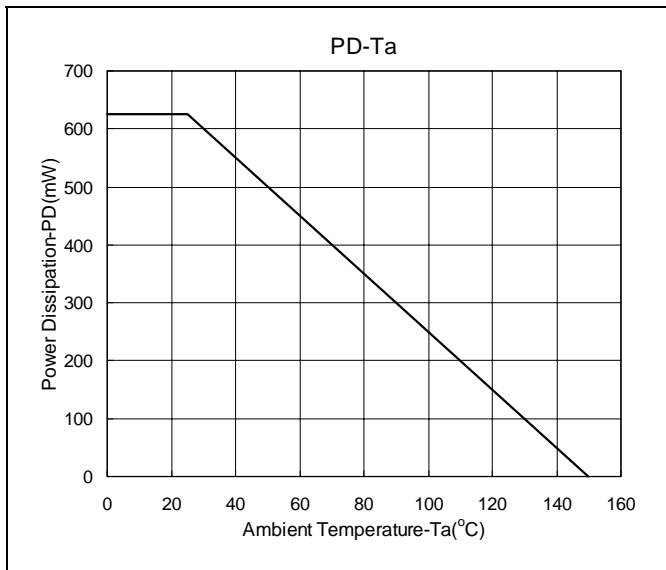
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-50	-	-	V	IC=-100uA
BVCEO	-50	-	-	V	IC=-1mA
BVEBO	-3	-	-	V	IE=-10uA
ICBO	-	-	-50	nA	VCB=-35V
IEBO	-	-	-50	nA	VEB=-3V
*VCE(sat)	-	-	-0.3	V	IC=-10mA, IB=-1mA
VBE(on)	-	-	-0.85	V	IC=-10mA, IB=-5V
*hFE1	250	-	800		VCE=-5V, IC=-0.1mA
*hFE2	250	-	-		VCE=-5V, IC=-1mA
*hFE3	250	-	-		VCE=-5V, IC=-10mA
fT	40	-	-	MHz	IC=-0.5mA, VCE=-5V, f=100MHz
Cob	-	-	4.0	pF	VCB=-5V, f=1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



Characteristics Curve







TO-92 Dimension

3-Lead TO-92 Plastic Package
HSMC Package Code : A

Marking :

HSMC Logo → □ □ □ □ ← Product Series
 Part Number → □ □ □ □ □ □
 Date Code → □ □ □ □ □ □ ← Rank
 Laser Mark

HSMC Logo
 Product Series
 Part Number → □ □ □ □ □ □
 Ink Mark

Style : Pin 1. Emitter 2. Base 3. Collector

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of HSMC.
- HSMC reserves the right to make changes to its products without notice.
- **HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- HSMC assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

Head Office And Factory :

- **Head Office** (Hi-Sincerity Microelectronics Corp.) : 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
 Tel : 886-2-25212056 Fax : 886-2-25632712, 25368454
- **Factory 1** : No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel : 886-3-5983621~5 Fax : 886-3-5982931
- **Factory 2** : No. 17-1, Ta-Tung Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel : 886-3-5977061 Fax : 886-3-5979220